IEEE Sapporo Section Annual Report 2019
February 17, 2020

PART A - SECTION SUMMARY

A.1 Executive Summary

- Section Executive Committee Member List
  - Chair: Takeo Ohgane
  - Vice Chair: Miki Haseyama
  - Secretary/Treasurer: Toshihiko Nishimura
  - Auditor: Hiroyumi Sanada, Hajime Igarashi
  - Chair of Fellow Nomination Committee: Kunimasa Saitoh
  - Chair of Membership Development Committee: Tatsuya Kashiwa
  - Chair of Student Activities Committee: Manabu Omiya
  - Chair of Publications Committee: Yuichi Fujino
  - Chair of Nominating Committee: Kenji Araki
  - Chair of Technical Program Committee: Yukinori Suzuki
  - Chair of Award Committee: Yoshikazu Miyano
  - Other Executive Committee Members: Kunitoshi Motoki, Naoto Yoshimoto, Tsuyoshi Yamamoto
  - Student Representative: Jianwen Xu

- Major Events (International, National)
  - 7 technical meetings were delivered.
  - We co-sponsored a domestic conference named 2019 Hokkaido-Section Joint Convention of Institutes of Electrical and Information Engineers which was held at Muroran Institute of Technology, Muroran, Hokkaido, Japan.
  - We supported 2019 Joint International Symposium on Electromagnetic Compatibility and Asia-Pacific International Symposium on Electromagnetic Compatibility (EMC Sapporo & APEMC 2019) which was held at Sapporo Convention Center, Sapporo, Hokkaido, Japan.
  - We supported the 26th International Display Workshops (IDW '19) which was held at Sapporo Convention Center, Sapporo, Hokkaido, Japan.

- Major Student and Affinity Group Activities
  - Muroran Institute of Technology Student Branch was established. Kick Off Event was held at Muroran Institute of Technology, Muroran, Hokkaido, Japan.
  - Hokkaido University and Muroran Institute of Technology Student Branches organized one special networking session in Hokkaido-Section Joint Convention of Institutes of Electrical and Information Engineers to exchange their experiences in university life. This session was co-organized with IEICE Hokkaido University Student Branch.
  - Sapporo Section WIE organized two lectures.

- Awards
  - We organized the following two types of student awards
    - IEEE Sapporo Section Student Paper Contest
    - IEEE Sapporo Section Student Paper Awards
  - 2019 Award ceremony was held in conjunction with 2020 Sapporo Section annual meeting.

A.2 Financial Report

- Summary (as per submitted on NetSuite)
  - Income: JPY 1,937,087
    - 3.10 - Rebate from IEEE HQ  
      - JPY 380,100
    - 3.16 - Region 10 Assessment  
      - JPY 454,763
    - 3.XX - Rebate from NVMSA2018  
      - JPY 1,102,205
    - 3.45 - Non-IEEE CB Account Interest  
      - JPY 19
  - Expense: JPY 922,724
    - 4.10 - Meetings & Social Events Expense  
      - JPY 31,338
    - 4.60 - Educational Activities Expense  
      - JPY 103,512
    - 4.80 - Student Activities Expense  
      - JPY 299,634
    - 4.90 - Other Program Expenses  
      - JPY 50,000
    - 5.20 - Travel Expense  
      - JPY 48,760
- 5.50 - Support to Sections/Chapters Expense JPY 386,324
- 5.60 - Other Management & General Expenses JPY 3,156

- Cash on Hand at Beginning of Year: JPY 1,547,195
- Cash on Hand at End of Year: JPY 2,561,558
PART B - ORGANIZATIONAL ACTIVITIES

B.1 Membership Development Activities

- Total number of active members in the past 3 years.
  - End of 2017: 270
  - End of 2018: 284
  - End of 2019: 334
- Summary and evidence of work done to improve the value of membership, which leads to retention and growth of members
  - 7 technical meetings
  - Support to new student members

B.2 Chapter Activities

- Total number of Chapters in the Section
  - No chapters other than joint chapters.
- Number of Chapters formed in the current year
  - None

B.3 Professional and Continuing Education Activities

Summary of continuing Educational activities including conferences, technical activities, training courses, and distinguished lecture programs.

The following 8 speakers were invited as educational/technical programs.

1. Schedule: Feb. 15, 2019, with IEICE Sapporo Section
   - Title: An Overview of Software Defined Networks and My Research Topics
   - Lecturer: Dr. Justin Lipman, Associate Professor of School of Computing and Communications, University of Technology, Sydney

2. Schedule: May 17, 2019,
   - Title: 5G Mobile Edge Computing: Research Roadmap of the H2020 5G-Coral Project
   - Speaker: Prof. Ying-Dar Lin, of National ChiaoTung University, Hsinchu, TAIWAN

3. Schedule: June 24-25, 2019, with Sapporo Section WIE
   - Title: Turbo Equalization; Its Information Theoretic Analysis and Relation to Lossy Forward Relaying Multi-Terminal Source Coding Systems
   - Speaker: Prof. Tad Matsumoto of Japan Advanced Institute of Science and Technology, Japan, and Center for Wireless Communications, University of Oulu
   - Title: Lossy Communications with Lossy-Forward Relaying and Lossy Coding
   - Speaker: Lin Wensheng of Japan Advanced Institute of Science and Technology, Japan

4. Schedule: Aug. 2, 2019,
   - Title: Privacy and Trust Issues in Vehicular Networks
   - Lecturer: Dr. Priyadarsi Nanda, Associate Professor of School Head of Electrical and Data Engineering, University of Technology, Sydney

5. Schedule: Aug. 27, 2019,
   - Title: 5G Mobile Networks – Technologies and Challenges
   - Lecturer: Prof. Abbas Jamalipour of Professor of Ubiquitous Mobile Networking School of Electrical and Information Engineering, The University of Sydney, Australia

   - Title: The Evolution of Data Center Network Architectures
   - Lecturer: Prof. Suresh Subramaniam of George Washington Univ.

7. Schedule: Nov. 25, 2019, with IEICE Hokkaido Section
   - Title: Kuruma no Daihennge "CASE" wo Buzurazu ni Horisagete miyo (in Japanese)
   - Lecturer: Dr. Akira Takahashi of DENSO, Japan

Sapporo Section co-sponsored, technically co-sponsored, or supported the following three conferences including one domestic ones.

1. We co-sponsored a domestic conference named 2019 Hokkaido-Section Joint Convention of Institutes of Electrical and Information Engineers which was held at Muroran Institute of Technology, Muroran, Hokkaido, Japan.
2. We supported 2019 Joint International Symposium on Electromagnetic Compatibility and Asia-Pacific International Symposium on Electromagnetic Compatibility (EMC Sapporo & APEMC 2019) which was held at Sapporo Convention Center, Sapporo, Hokkaido, Japan.

3. We supported the 26th International Display Workshops (IDW ’19) which was held at Sapporo Convention Center, Sapporo, Hokkaido, Japan.

B.4 Students Activities

- Total number of Student Branches in the Section
  - Two student branches (Hokkaido University and Muroran Institute of Technology)

- Number of Student Branches formed in the current year
  - One (Muroran Institute of Technology)

- Section level student activities (student congress, paper and other contests, awards etc)
  - IEEE Sapporo Section Student Paper Contest
    We awarded thirteen (13) excellent student presenters at Hokkaido-Section Joint Convention of Institutes of Electrical and Information Engineers.
  - IEEE Sapporo Section Student Paper Awards
    We awarded five (5) excellent student authors whose papers were published in the IEEE Transactions, Journals, and/or Proceedings.

- Number of active Student Branches (Student Branches who have reported required number of meetings during the year)
  - Two student branches (Hokkaido University and Muroran Institute of Technology)

- Summary of Student Branch activities (Student Branch wise with attachment table/information)
  - In 2019, Student Branches in Hokkaido University and Muroran Institute of Technology organized one special networking session in Hokkaido-Section Joint Convention of Institutes of Electrical and Information Engineers to exchange their experiences in university life. This session was co-organized with IEICE Hokkaido University Student Branch.

B.5 Affinity Group Activities

- Young Professional (YP)
  - No YP in this section.

- Women In Engineering (WIE)
  - One technical meeting was jointly held with Sapporo Section and one lecture was jointly held with IEICE Sapporo Section.

- Life Member
  - No affinity group of this type in this section.

B.6 Awards & Recognition Activities

None

B.7 Communication Activities (Newsletter, Home Page, E-mail etc.)

- Home Page of the Section (give the URL and how often it is updated)
  - Section’s web page:
    https://www.ieee-jp.org/section/sapporo/
  - Sapporo Section WIE:
    https://www-lmd.ist.hokudai.ac.jp/WIE_Sapporo/
  - Student Branch at Hokkaido University
    https://csw.ist.hokudai.ac.jp/ieee/
  - Student Branch at Muroran Institute of Technology
    http://www3.muroran-it.ac.jp/enes/student_branch/

- Other means of contacts with Section members including social media
  - eNotice

B.8 Industry Relations

None
B.9 Humanitarian Technology Activities

None

B.10 Community Activities

None
PART C - OTHERS

C.1 Special Events
None.

C.2 Relationship with National and International Societies and Non-Government Organizations (NGO)
None.

C.3 Collaboration with other IEEE Sections
None.

C.4 Support extended to Sub-sections & Society Chapters within the Section
None.

C.5 Best Practices of your Section (which you would like to share with other Sections for the benefits of members)
None.

C.6 Problems anticipated and suggestions for solutions, if any
None.

PART D - GOALS AND PLANS

D.1 Continuation of project/activity in progress and their implementation plans
We are planning to organize technical lectures, symposiums, workshops on topics of interests. In some cases, these might be in collaborations with other institutes.

D.2 Goals and Future Plans
- Increasing the membership
- Enhancing the student activities
- Nominations of members for Senior Member and Fellow of the Institute
- Providing better services to the members
- Establishing new student branches and/or a YP affinity group

D.3 Any innovative ideas to make IEEE more creative and value added for sustaining the membership retention and recruitment goals.
We do not have any actual ideas. We would like to discuss this issue in the section.

We do not have any actual plan yet. We would like to discuss this issue in the section.